

IN THE CLAIMS

Claims 1-17 (Previously deleted)

1 Claim 18 (currently amended). A substrate for ~~re-orienting~~ receiving a die-down
2 die and providing electrical contacts re-orientated into ~~to~~ a die-up orientation, the die-
3 down die defining electrical contacts, the substrate comprising:
4 a plurality of electrically conductive ~~leads~~ traces defining first contacts,
5 the first contacts arranged to accept connector wires making electrical connections from
6 the electrical contacts of a die-down die, and
7 wherein the electrical ~~leads~~ traces define second contacts, the second con-
8 tacts arranged to correspond to the die-up orientation,
9 wherein the substrate can be placed into a package designed to accept a
10 die-up die, and wherein electrical connections may be made to the substrate's second
11 contacts as if it were a die-up die.

1 Claim 19 (currently amended). The substrate of claim 18 further comprising:
2 a die-down die mounted to the substrate,
3 ~~electrically conductive connector~~ wires joining the electrical contacts of
4 the die-down die to the first contacts on the ~~substrate~~ conductive traces,
5 ~~a package arranged to receive a die-up die, the package with third contacts~~
6 ~~arranged for making electrical connection to a die-up die, and~~
7 electrically conductive wires joining the second contacts on the ~~substrate~~
8 conductive traces to the lead frame contacts contacts on a lead frame.

Claim 20. (deleted).

1 Claim 21. (currently amended). The substrate of claim 19 further comprising
2 non-conductive means for attaching the substrate to the die-down die.

1 Claim 22. (currently amended). The substrate of claim ~~19~~18 wherein the sub-
2 strate comprises a material selected from the groups consisting of ceramic and organic.

1 Claim 23. (previously added). The substrate of claim 19 wherein the die-down
2 die is an integrated circuit.

Claim 24. (deleted).

Claims 25-31 (withdrawn).

Claim 32 (deleted).

Claim 33. (deleted).

1 Claim 34. (currently amended). The die attach package of claim ~~32~~45 further
2 comprising non-conductive means for attaching the substrate to ~~the~~ a die-down die.

1 Claim 35. (currently amended). The die attach package of claim ~~32~~45 wherein
2 the substrate comprises a material selected from the groups consisting of ceramic and or-
3 ganic.

1 Claim 36. (currently amended). The die attach package of claim ~~32~~45 wherein
2 the die-down die is an integrated circuit.

1 Claim 37. (currently amended). The die attach package of claim ~~32~~45 wherein
2 the die-down die includes components attached to the die-down die.

Claim 38-41. (Withdrawn).

1 Claim 42. (currently amended). The process of claim 38 further comprising the
2 step of forming the substrate from a material selected from the groups consisting of ce-
3 ramic and organic.

1 Claim 43. (previously added). The process of claim 38 wherein the die-down die
2 is an integrated circuit.

1 Claim 44. (currently amended). The process of claim 38 wherein the die-down
2 die includes components attached to the die-down die.

1 Claim 45 (new). A die attach package for receiving a die with contacts arranged
2 in a die-up orientation, the die attach package comprising:
3 a substrate as defined in claim 18,
4 a lead frame with contacts,
5 connector wires joining the second contacts on the traces to the lead frame
6 contacts, wherein the lead frame also provides means to make electrical connection to a
7 printed circuit board.